Title (en)
Substrate processing apparatus and substrate processing method

Title (de)
Substratverarbeitungsvorrichtung

Title (fr)
Dispositif de traitement de substrats

Publication
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Application
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Abstract (en)
Thermal processing unit sections each with ten tiers and coating processing unit sections each with five tiers are disposed around a first main wafer transfer section and a second main wafer transfer section, and in the thermal processing unit section, the influence of the time required for substrate temperature regulation processing on a drop in throughput can be reduced greatly by transferring the wafer W while the temperature of the wafer W is being regulated by a temperature regulation and transfer device.

IPC 8 full level
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Citation (search report)
- [X] US 5942013 A 19990824 - AKIMOTO MASAMI [JP]
- [X] EP 0786800 A2 19970730 - TOKYO ELECTRON LTD [JP]
- [X] EP 0841688 A2 19980513 - TOKYO ELECTRON LTD [JP]
- [X] US 5826129 A 19981020 - HASEBE KEIZO [JP], et al

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EP 1094501 A2 20010425; **EP 1094501 A3 20030820**; **EP 1094501 B1 20070228**; **EP 1094501 B9 20071031**; DE 60033613 D1 20070412;
DE 60033613 T2 20071108; DE 60043628 D1 20100211; DE 60045588 D1 20110310; EP 1770760 A1 20070404; EP 1770760 B1 20130403;
EP 1770761 A1 20070404; EP 1770761 B1 20091230; EP 1770762 A1 20070404; EP 1770762 B1 20110126; EP 1770763 A1 20070404;
KR 100634122 B1 20061016; KR 20010051079 A 20010625; SG 123602 A1 20060726; SG 123603 A1 20060726; SG 123604 A1 20060726;
SG 90184 A1 20020723; TW 480555 B 20020321; US 2002118973 A1 20020829; US 2003012575 A1 20030116; US 6402401 B1 20020611;
US 6471422 B2 20021029; US 6672779 B2 20040106

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SG 200401388 A 20001018; SG 200401389 A 20001018; SG 200401390 A 20001018; TW 89121807 A 20001018; US 12233302 A 20020416;
US 24475502 A 20020917; US 68814000 A 20001016